**P-Ch MOSFET** 

## **General Description**

The WSF45P06 is the highest performance trench P-ch MOSFETs with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSF45P06 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

## **Product Summery**

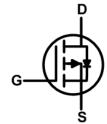
BVDSS	RDSON	ID
-60V	40mΩ	-45A

# **Applications**

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- CCFL Back-light Inverter

## **TO-252 Pin Configuration**





# **Absolute Maximum Ratings**

Symbol	Parameter Rating		Units
$V_{DS}$	Drain-Source Voltage	-60	V
$V_{GS}$	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, -V <sub>GS</sub> @ -10V <sup>1</sup>	-45	Α
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, -V <sub>GS</sub> @ -10V <sup>1</sup> -38		А
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup> -90		А
EAS	Single Pulse Avalanche Energy <sup>3</sup> 66		mJ
I <sub>AS</sub>	Avalanche Current	-27.2	А
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup> 31.3		W
T <sub>STG</sub>	Storage Temperature Range -55 to 150		$^{\circ}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^{\circ}$

## **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	nce Junction-Ambient <sup>1</sup> 62		°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		4	°C/W



# P-Channel Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS}$ =0 $V$ , $I_D$ =-250 $u$ A	-60			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =-1mA		-0.012		V/°C
D	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V , I <sub>D</sub> =-18A		30	40	0
R <sub>DS(ON)</sub>		V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-12A		52	65	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V -V 1 - 2500A	-1.0	-1.6	-2.5	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=-250uA$		4.32		mV/℃
-	Drain Source Leakage Current	V <sub>DS</sub> =-32V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1	uA
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-32V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20 V$ , $V_{DS}$ = $0 V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =-5V , I <sub>D</sub> =-18A		12.6		S
$R_g$	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		13	16	Ω
$Q_g$	Total Gate Charge (-4.5V)			4.1		
$Q_gs$	Gate-Source Charge	V <sub>DS</sub> =-20V , V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-12A		4.9		nC
$Q_gd$	Gate-Drain Charge			5.6		
T <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD}$ =-15V , $V_{GS}$ =-10V , $R_{G}$ =3.3 $\Omega$ , $I_{D}$ =-1A		19.2		
T <sub>r</sub>	Rise Time			12.8		
T <sub>d(off)</sub>	Turn-Off Delay Time			48.6		ns
T <sub>f</sub>	Fall Time			4.6		
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-15V , V <sub>GS</sub> =0V , f=1MHz		1914		
Coss	Output Capacitance			158		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			116		

## **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	V <sub>DD</sub> =-25V , L=0.1mH , I <sub>AS</sub> =-15A	20			mJ

## **Diode Characteristics**

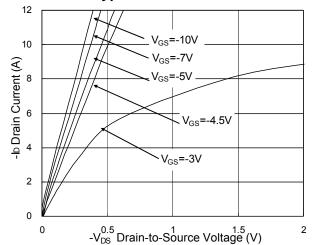
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,6</sup>	-V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			-23	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>				-46	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25℃			-1	V

#### Note

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper,t<10sec.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =-25V, $V_{GS}$ =-10V,L=0.1mH,I<sub>AS</sub>=-20A
- 4.The power dissipation is limited by 150  $^{\circ}\mathrm{C}$  junction temperature
- 5.The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



# **P-Channel Typical Characteristics**



**Fig.1 Typical Output Characteristics** 

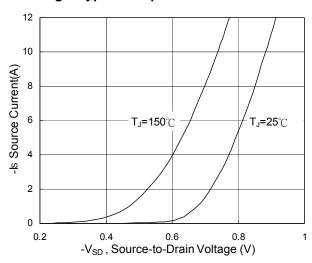


Fig.3 Forward Characteristics of Reverse

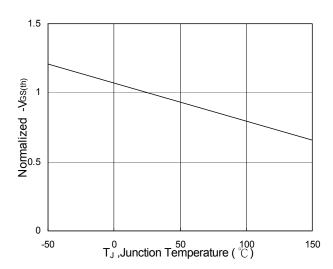


Fig.5 Normalized V<sub>GS(th)</sub> v.s T<sub>J</sub>

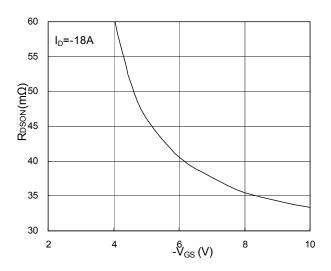


Fig.2 On-Resistance v.s Gate-Source

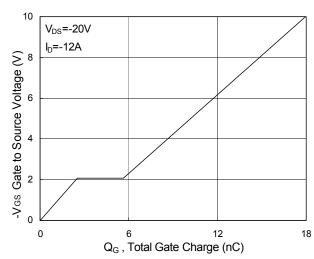


Fig.4 Gate-Charge Characteristics

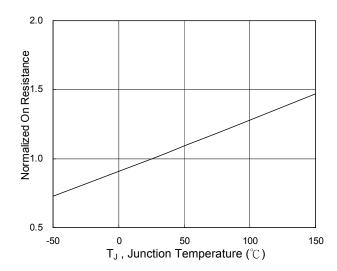
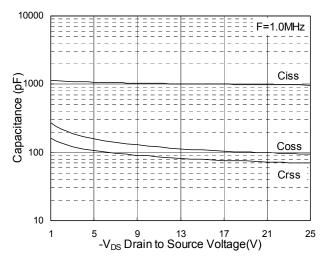


Fig.6 Normalized R<sub>DSON</sub> v.s T<sub>J</sub>





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Fig.7 Capacitance

Fig.8 Safe Operating Area

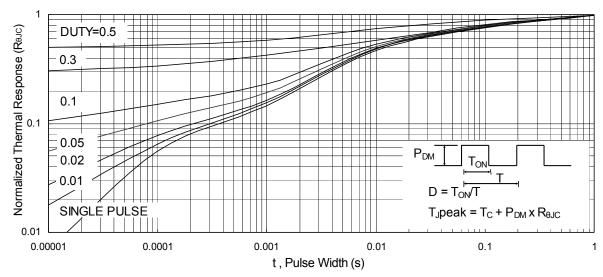
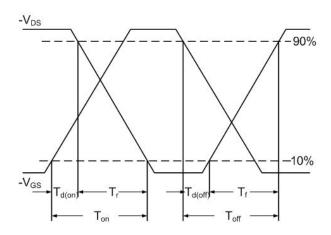


Fig.9 Normalized Maximum Transient Thermal Impedance



EAS= 1/2 L x (-I<sub>AS</sub><sup>2</sup> )x -BV<sub>DSS</sub> -BV<sub>DSS</sub> -V<sub>DD</sub>

Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Waveform



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